

IN THE CLAIMS

Please cancel Claims 5-7 and 9-13 without prejudice or disclaimer.

Please add the following new Claims:

New Claim 14. A semiconductor package comprising:

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a semiconductor die having means for receiving light from outside of the package, and a substantially planer surface opposite of the means, wherein a plurality of bond pads are disposed on the periphery of the means;

a plurality of conductive bumps coupled to the bond pads; and
a glass having a substantially planar first surface and a substantially planar second surface, wherein a plurality of electrically conductive patterns are formed near the circumference of the second surface, each of the conductive patterns having a first contact in electrical contact with an associated one of the conductive bumps.

New Claim 15. The semiconductor package of Claim 14, further comprising a plurality of conductive balls having a diameter greater than a height of the semiconductor die, wherein the conductive balls are each fused to a second contact of an associated one of the electrically conductive patterns.

New Claim 16. The semiconductor package of Claim 14, wherein the glass further includes channels formed between the second surface thereof and an end thereof, the conductive patterns being formed in the channels.

New Claim 17. The semiconductor package of Claim 14, wherein the conductive patterns are patterns etched from a conductive layer disposed on the glass.

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New Claim 18. A semiconductor package comprising:
a semiconductor die having means for receiving light from outside of the package, and a substantially planer surface opposite of the means and having a plurality of electrical contacts;
means for connecting signals from the semiconductor die to an external device; and
a glass for permitting light to enter the semiconductor package and pass to the means for receiving light, the glass including means for connecting the plurality of electrical contacts to the means for connecting signals.

CLEAN VERSION OF NEW CLAIMS

Claim 14. A semiconductor package comprising:

a semiconductor die having means for receiving light from outside of the package, and a substantially planer surface opposite of the means, wherein a plurality of bond pads are disposed on the periphery of the means;

a plurality of conductive bumps coupled to the bond pads; and

a glass having a substantially planar first surface and a substantially planar second surface, wherein a plurality of electrically conductive patterns are formed near the circumference of the second surface, each of the conductive patterns having a first contact in electrical contact with an associated one of the conductive bumps.

Claim 15. The semiconductor package of Claim 14, further comprising a plurality of conductive balls having a diameter greater than a height of the semiconductor die, wherein the conductive balls are each fused to a second contact of an associated one of the electrically conductive patterns.

Claim 16. The semiconductor package of Claim 14, wherein the glass further includes channels formed between the second surface thereof and an end thereof, the conductive patterns being formed in the channels.

Claim 17. The semiconductor package of Claim 14, wherein the conductive patterns are patterns etched from a conductive layer disposed on the glass.

Claim 18. A semiconductor package comprising:

a semiconductor die having means for receiving light from outside of the package, and a substantially planer surface opposite of the means and having a plurality of electrical contacts;

means for connecting signals from the semiconductor die to an external device; and

a glass for permitting light to enter the semiconductor package and pass to the means for receiving light, the glass including means for connecting the plurality of electrical contacts to the means for connecting signals.